

Customer's Confirmation

Version: 2.0

Technical Specification

MODEL NO: VB3300-EHB (ED058TC8)

The content of this information is subject to be changed without notice. Please contact E lnk or its agent for further information.

Customer	_
Date	_
Ву	_
	☐E Ink's Confirmation

Approval by

Confirmed by

Prepared by



Revision History

Rev.	Issued Date	Revised / Contents
1.0	March ,3 , 2021	Initial
2.0	Jun ,7 , 2021	Remove Mylar, Modify ME drawing page 5



TECHNICAL SPECIFICATION

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1. General Description

VB3300-EHB is a reflective electrophoretic E Ink[®] technology display module based on active matrix TFT substrate. It has 5.84" active area with 720 x 1440 pixels, the display is capable to display images at 2-16 gray levels (1-4 bits) depending on the display controller and the associated waveform file it used.

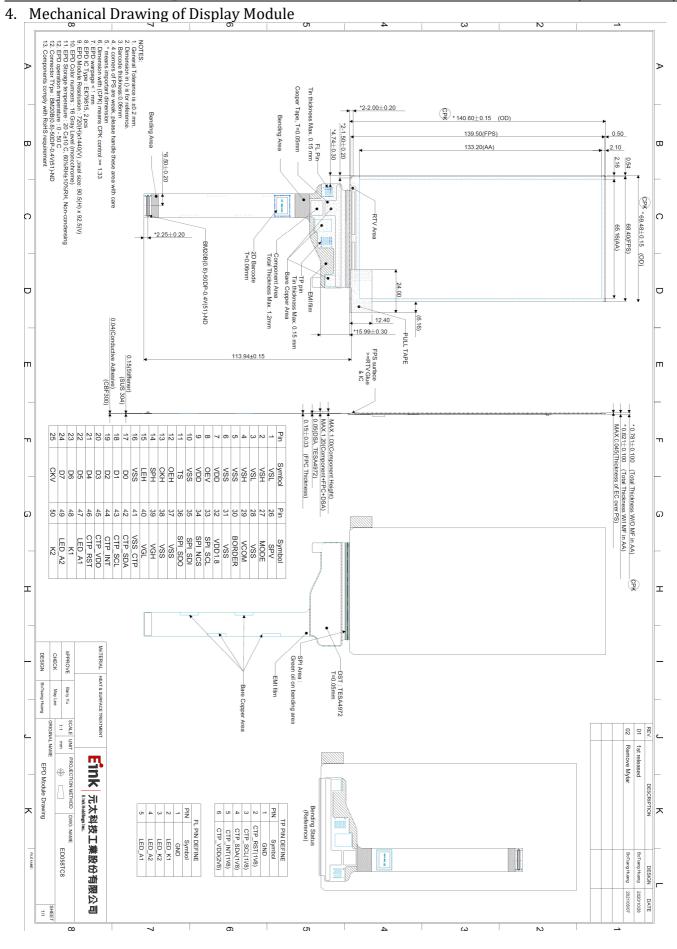
2. Features

- ➤ Carta High contrast reflective/electrophoretic technology
- > 720 x 1440 display
- ➤ High reflectance
- > Ultra wide viewing angle
- > Ultra low power consumption
- > Pure reflective mode
- ➤ Bi-stable
- Commercial temperature range
- > Portrait mode

3. Mechanical Specifications

Parameter	Specifications	Unit	Remark
Screen Size	5.84	Inch	
Display Resolution	720 (H)×1440(V)	Pixel	
Active Area	65.16 (H)×133.2 (V)	mm	
Pixel Pitch	90.5 (H) × 92.5 (V)	μ m	
Pixel Configuration	Rectangle		
Outline Dimension	69.48 (W) × 140.60 (H) × 0.78 (D)	mm	w/o PF
Module Weight	17.0+/-1.7	g	
Number of Gray	16 Gray Level (monochrome)		
Display operating mode	Reflective mode		







5. Input/output Interface

5-1) Connector type: BM20B(0.8)-50DP-0.4V(51)-ND

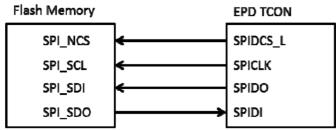
5-2) Pin Assignment

Pin #	Signal	I/O	Description	Remark
1	V _{SH}	Р	Negative power supply source	
2	V _{SH}	Р	Positive power supply source driver	
3	V_{SL}	Р	Negative power supply source	
4	V _{SH}	Р	Positive power supply source driver	
5	V_{SS}	Р	Ground	
6	Vss	Р	Ground	
7	V_{DD}	Р	Digital power supply drivers (3.3V)	
8	OEV	1	Output enable of gate driver	
9	V_{DD}	Р	Digital power supply drivers (3.3V)	
10	Vss	Р	Ground	
11	TS	-	Thermistor sensor	NCP15XH103F03RC
12	OEH	l	Output enable source driver	
13	СКН	I	Clock of source driver	
14	SPH	I	Start pulse of source driver	
15	LEH	l	Latch enable of source driver	
16	V _{SS}	Р	Ground	
17	D0	I	Data signal source driver	
18	D1	l	Data signal source driver	
19	D2	I	Data signal source driver	
20	D3	l	Data signal source driver	
21	D4	I	Data signal source driver	
22	D5	l	Data signal source driver	
23	D6	l	Data signal source driver	
24	D7	I	Data signal source driver	
25	CKV	1	Clock of gate driver	
26	SPV	I	Start pulse of gate driver	
27	MODE	1	Output mode selection gate driver	
28	Vss	Р	Ground	
29	V _{COM}	Р	Common connection	
30	Border	Р	Border connection	
31	V_{SS}	Р	Ground	
32	$V_{\text{DD1.8}}$	Р	SPI flash power supply (1.8V)	
33	SPI_SCL	I	Serial Data Clock for Flash memory	
34	SPI_NCS	I	Chip Select for Flash memory	
35	SPI_SDI	l	Serial Data Input for Flash memory	
36	SPI_SDO	I	Serial Data Output for Flash	
37	Vss	Р	Ground	
38	Vss	Р	Ground	

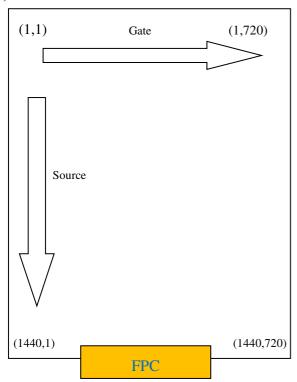
VB3300-EHB (ED058TC8)

39	V_{GH}	Р	Positive power supply gate	
40	V_{GL}	Р	Negative power supply gate	
41	V _{SS CTP}	Р	CTP Ground	
42	CTP SDA	I	Touch signal	
43	CTP SCL	I	Touch signal	
44	CTP INT	I	Touch signal	
45	CTP VDD	I	Touch signal	
46	CTP RST	I	Touch signal	
47	NC	-	NO Connection	
48	K1	-	Front light signal	
49	А	=	Front light signal	
50	K2	-	Front light signal	

Note 5-1



5-3) Panel Scan Direction





6. Electrical Characteristics

6-1) Absolute Maximum Ratings:

Parameter	Symbol	Rating	Unit	Remark
Logic Supply Voltage	VDD_3V3	-0.3 to 5.0	V	
Positive Supply Voltage	V_{SH}	-0.3 to +18	V	
Negative Supply Voltage	V_{SL}	-18 to +0.3	V	
Max .Drive Voltage Range	V _{SH} – V _{SL}	36	V	
Supply Voltage	VGH	-0.3 to 46	V	
Supply Voltage	VGL	-25 to +0.3	V	
Supply Range	VGH-VGL	-0.3 to +46	V	
Operating Temp. Range	TOTR	0 to +50	°C	
Storage Temperature	TSTG	-25 to 75	°C	

6-2) Panel DC Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Signal ground	Vss		-	0	-	V
	V _{DD_3V3}		3.0	3.3	3.6	V
Logic Voltage supply	I _{VDD_3V3}	V _{DD} =3.3V	-	7.9	8.4	mA
CDI Vallacia de al	V_{DD_1V8}		1.65	1.8	1.95	V
SPI Voltage supply	I _{VDD_1V8}	V _{DD_1V8} =1.8V	1		1.5	mA
Gate Negative supply	V _{GL}		-22	-21	-20	V
date Negative Supply	I _{GL}	V _{GL} =-20V	-	5.6	25	mA
Cata Dasitiva supply	V_{GH}		21	22	23	V
Gate Positive supply	Ідн	V _{GH} =22V	-	3.2	4.2	mA
Source Negative supply	V _{SL}		-15.4	-15	-14.6	V
Source Negative Supply	Isl	V _{SL} =-15V	-	7.9	92	mA
Course Doo'thing annuals	V_{SH}		14.6	15	15.4	V
Source Positive supply	I _{SH}	V _{SH} =15V	-	6.4	107	mA
Border supply	V _{COM}		-	Adjusted	-	V
Asymmetry source	V_{Asym}	V _{SH} + V _{SL}	-800	0	800	mV
Common voltage	V _{сом}		-4	Adjusted	-0.5	V
Common voitage	Ісом		-	4.4	5.2	mA
Total Power	Р		-	422	3625	mW
Standby power	P _{STBY}		-	-	0.4	mW

- The maximum power consumption is measured using 85 Hz waveform with following pattern transition: from pattern of repeated 1 consecutive black scan lines followed by 1 consecutive white scan line to that of repeated 1 consecutive white scan lines followed by 1 consecutive black scan lines. (Note 6-1)
- The Typical power consumption is measured using 85 Hz waveform with following pattern transition:

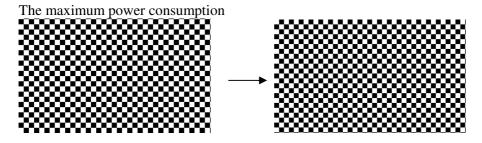




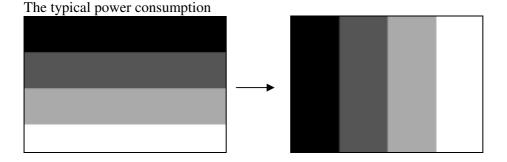
from horizontal 4 gray scale pattern to vertical 4 gray scale pattern. (Note 6-2)

- The standby power is the consumed power when the panel controller is in standby mode.
- The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by E Ink.
- Vcom is recommended to be set in the range of assigned value $\pm 0.1 \text{ V}$
- The maximum I_{COM} inrush current is about 600 mA

Note6-1



Note 6-2

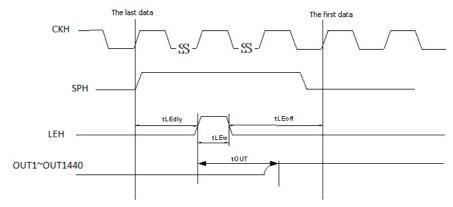




6-4) Panel AC characteristics

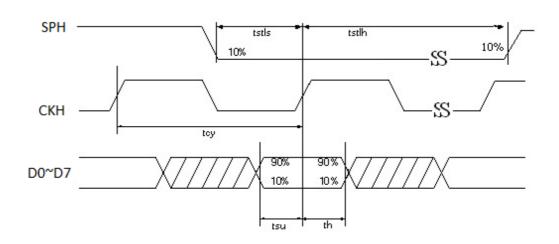
Parameter	Symbol	Min.	Тур.	Max.	Unit
Clock frequency	fckv			200	kHz
Minimum "L" clock pulse width	twL	0.5			us
Minimum "H" clock pulse width	twH	0.5			us
Clock rise time	trckv			100	ns
Clock fall time	tfckv			100	ns
SPV setup time	tSU	100		twH-100	ns
SPV hold time	tH	100		twH-100	ns
Pulse rise time	trspv			100	ns
Pulse fall time	tfspv			100	ns
Clock CKH cycle time	tcy	16.67	50		ns
D0 D7 setup time	tsu	8			ns
D0 D7 hold time	th	8			ns
SPH setup time	tstls	0.5*tcy		0.8*tcy	ns
SPH hold time	tstlh	0.5*tcy		240*tcy-tstls	ns
LEH on delay time	tLEdly	3.5*tcy			ns
LEH high-level pulse width (When VDD=1.7V to 2.1V)	tLEw	300			ns
LEH off delay time	tLEoff	200			ns
Output setting time to +/- 30mV(Cload=200pF)	tout			20	us

OUTPUT LATCH CONTROL SIGNALS

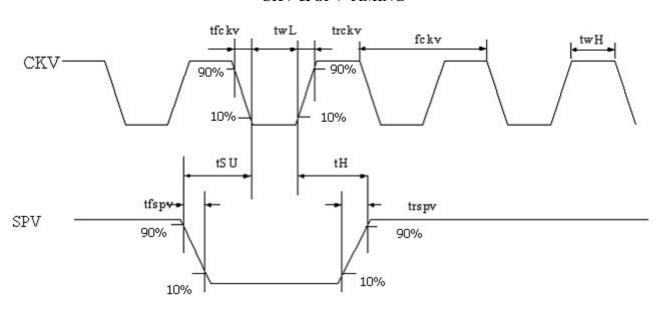


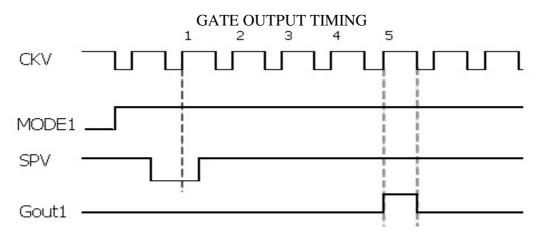
CLOCK & DATA TIMING





CKV & SPV TIMING





Note: First gate line on timing after 5CKV gate line is on



6-5) Refresh Rate

The module is applied at a maximum refresh rate of 85 Hz.

	Min	Max
Refresh Rate	-	85 Hz

7-6) Controller Timing

This timing mode is depicted on Figure 1 and Figure 2 and it refers to timing of Source Driver Output Enable (OEH) and Gate Driver Clock (CKV). Note, that in this mode LGON follows CKV timing.

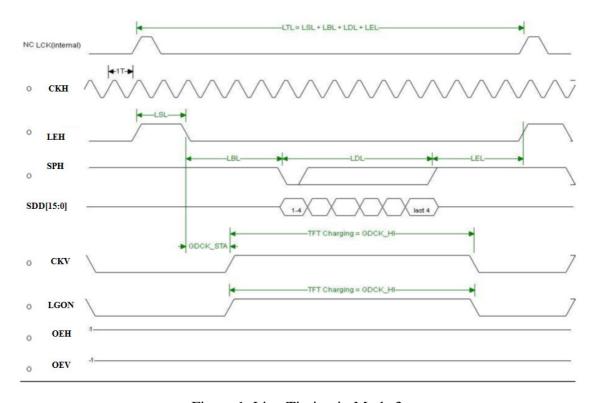


Figure 1. Line Timing in Mode 3



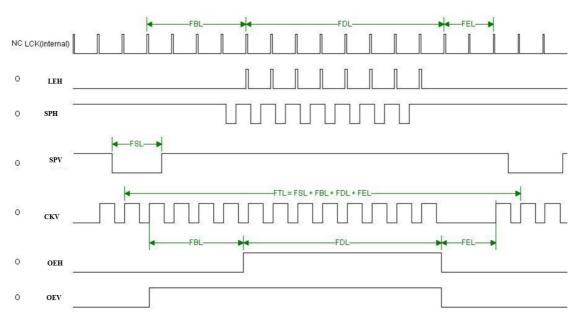


Figure 2 Frame Timing in Mode 3

Timing Parameters Table

inning ratameters racte						
Mode CKH [MHz]	3 24	Resolution				
Pixels Per CKH	4					
Line	LSL					LGONL
Parameters[CKH]	10	6	360	6	4	354
Line	-					1
Parameters[us]	0.42	0.25 15.00 0.25 0.17 14.75				
Frame	FSL	FBL FDL FEL - FR [Hz]				
Parameters [lines]	1	4	720	14	-	85.02
Frame	-					
Parameters [us]	15.92	63.67 11460.00 222.83				

Note 1: For parameters definition, see Section 7. Active Matrix Electronic Paper Display Timings

Note 2: For Isis Controller CKV_STA and LGONL are not settable parameters; CKV_STA = LBL,

LGONL = LDL + 0.5

Note 3: For Freescale SoC OEV Low pulse represent FSL and SPV pulses with the first period of FBL

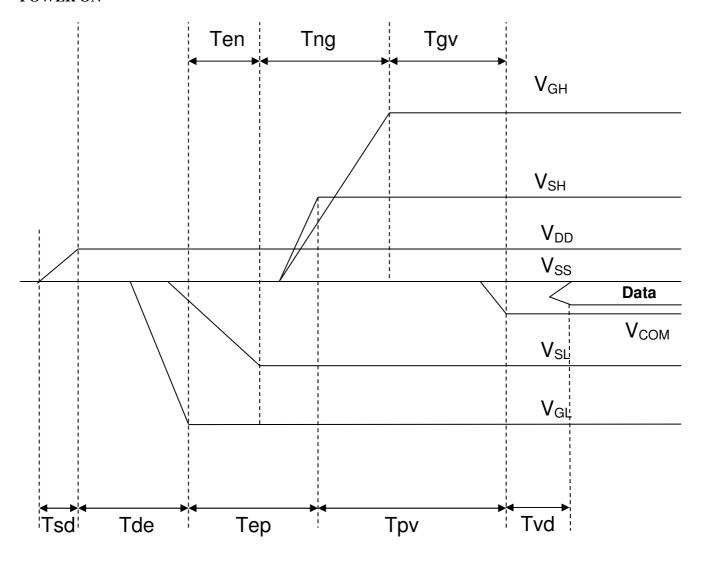


7. Power Sequence

Power Rails must be sequenced in the following order:

- 1. $V_{SS} \rightarrow V_{DD} \rightarrow V_{SL} \rightarrow V_{SH}$ (Source Driver) $\rightarrow V_{COM}$
- 2. $V_{SS} \rightarrow V_{DD} \rightarrow V_{GL} \rightarrow V_{GH}$ (Gate Driver)

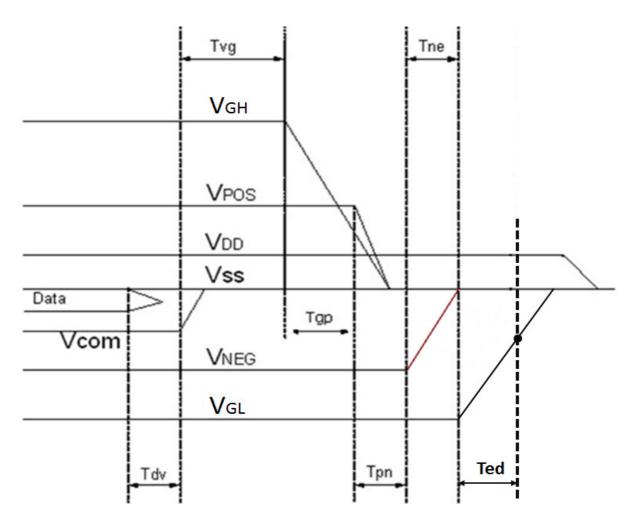
POWER ON



	Min	Max
Tsd	30us	-
Tde	100us	-
Тер	1000us	-
Трv	100us	-
Tvd	100us	-
Ten	Ous	-
Tng	1000us	-
Tgv	100us	-



POWER OFF



	Min	Max	Remark
Tdv	100μs	-	-
Tvg	0μs	-	-
Tgp	0μs	-	-
Tpn	0μs	-	-
Tne	0μs	-	-
Ted	0.5s	-	Discharged point @ -7.4 Volt

Note 7-1: Supply voltages decay through pull-down resistors.

Note 7-2 : Begin to turn off V_{GL} power after V_{SL} and V_{SH} are completely or almost discharged to GND state.

Note 7-3: V_{GL} must remain negative of Vcom during decay period



8. Optical characteristic

8-1) Specification

Measurements are made with that the illumination is under an angle of 45 degrees, the detector is perpendicular unless otherwise specified.

 $T = 25^{\circ}C$

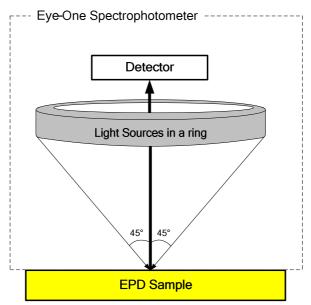
Symbol	Parameter	Conditions	Min	Тур.	Max	Unit	Note
R	Reflectance	White	35	45	-	%	Note 8-1
Gn	N _{th} Grey Level	-	-	DS+(WS-DS) ×n/(m-1)	-	L*	-
CR	Contrast Ratio	-	10	16	-		-

WS: White state , DS: Dark state, Gray state from Dark to White :DS \cdot G1 \cdot G2... \cdot Gn... \cdot Gm-2 \cdot WS m:4 \cdot 8 \cdot 16 when 2 \cdot 3 \cdot 4 bits mode

Note 8-1: Luminance meter: Eye – One Pro Spectrophotometer

8-2) Definition of contrast ratio

The contrast ratio (CR) is the ratio between the reflectance in a full white area (RI) and the reflectance in a dark area (Rd): CR = RI / Rd



8-3) Reflection Ratio

The reflection ratio is expressed as:

 $R = Reflectance Factor_{white board} \times (L_{center} / L_{white board})$

L_{center} is the luminance measured at center in a white area (R=G=B=1). L_{white board} is the luminance of a standard white board.





9. Handing, Safety and Environment Requirements and Remark

WARNING

The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

REMARK

All The specifications listed in this document are guaranteed for module only. Post-assembled operation or component(s) may impact module performance or cause unexpected effect or damage and therefore listed specifications is not warranted after any Post-assembled operation.

CAUTION

The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components.

Disassembling the display module can cause permanent damage and invalidate the warranty agreements.

IPA solvent can only be applied on active area and the back of a glass. For the rest part, it is not allowed.

Mounting Precautions

- (1) It's recommended that you consider the mounting structure so that uneven force (ex. Twisted stress) is not applied to the module.
- (2) It's recommended that you attach a transparent protective plate to the surface in order to protect the EPD. Transparent protective plate should have sufficient strength in order to resist external force.
- (3) You should adopt radiation structure to satisfy the temperature specification.
- (4) Acetic acid type and chlorine type materials for the cover case are not desirable because the former generates corrosive gas of attacking the PS at high temperature and the latter causes circuit break by electro-chemical reaction.
- (5) Do not touch, push or rub the exposed PS with glass, tweezers or anything harder than HB pencil lead. And please do not rub with dust clothes with chemical treatment. Do not touch the surface of PS for bare hand or greasy cloth. (Some cosmetics deteriorate the PS)
- (6) When the surface becomes dusty, please wipe gently with absorbent cotton or other soft materials like chamois soaks with petroleum benzene. Normal-hexane is recommended for cleaning the adhesives used to attach the PS. Do not use acetone, toluene and alcohol because they cause chemical damage to the PS.



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(7) Wipe off saliva or water drops as soon as possible. Their long time contact with PS causes deformations and color fading.

Data sheet status					
Product	This data sheet contains formal product specifications.				
specification					

Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.



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10. Reliability test

	TEST	CONDITION	METHOD	REMARK
1	High-Temperature Operation	T = +50°C, RH = 30% for 240 hrs	IEC 60 068-2-2Be	
2	Low-Temperature Operation	T = 0°C for 240 hrs	IEC 60 068-2-1Ae	
3	Low-Temperature Storage	T = -25°C for 240 hrs Test in white pattern	IEC 60 068-2-1Ab	
4	High-Temperature, High-Humidity Operation	T = +40°C, RH = 90% for 168 hrs	IEC 60 068-2-78	
5	High Temperature Storage	$T = +60^{\circ}C$, RH=26% for 240 hrs Test in white pattern	IEC 60 068-2-78	
6	Temperature Cycle	-25°C →+70°C, 100 Cycles 30min 30min Test in white pattern	IEC 68-2-14 Nb	
7	Solar radiation test	765 W/m² for 168hrs,40°C Test in white pattern	IEC60 068-2-5Sa	
8	Electrostatic Effect (non-operating)	(Machine model)+/- 250V 0Ω, 200pF	IEC 62180	

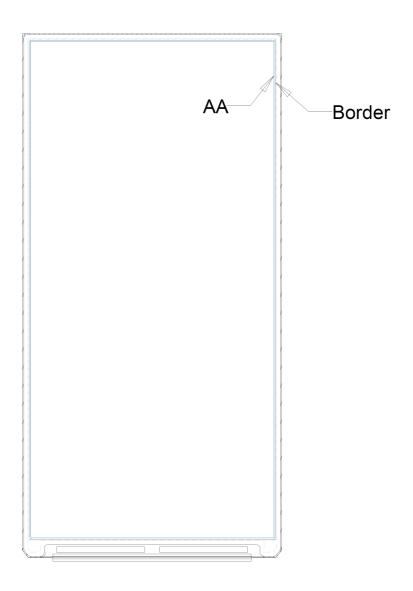
Actual EMC level to be measured on customer application Note: The protective film must be removed before temperature test.

< Criteria >

In the standard conditions, there is not display function NG issue occurred. (Including: line defect, no image). All the cosmetic specification is judged before the reliability stress.

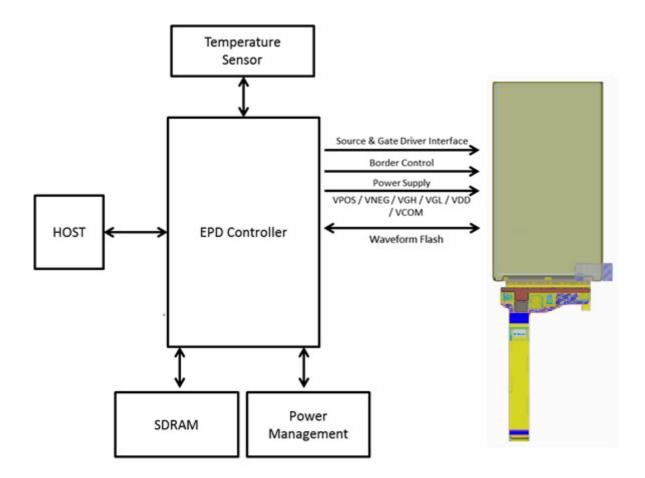


11. Border definition





12. Block Diagram





13. Packing

